

STACK INFORMATION

REVISIONS

REV	DESCRIPTION	DATE	APPROVED
01	PROTO RELEASE	11/04/14	
02	UPDATED AS PER 630-60194-01 REV02 SCHEMATICS	15/05/14	
03	FIXED DFA ISSUES, NET ADDED FOR J7.4	09/06/14	
04	IMPLEMENTED SILKSCREEN AND FAB CHANGES	12/06/14	

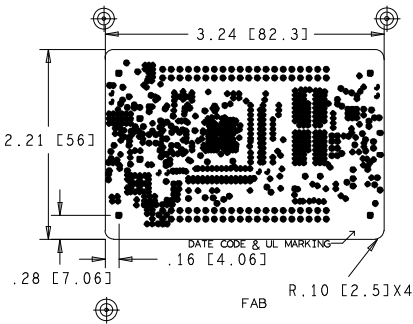
- NOTES:(UNLESS OTHERWISE SPECIFIED)
1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
 2. MATERIAL:
 - A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
 - B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
 - C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
 3. DRILLING:
 - A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003 TOL. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
 - B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
 4. PLATING:

COPPER PLATING IN THRU-HOLES .001 min.
 5. MARKING:
 - A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
 - B.FABRICATOR TO PLACE DATE CODE AND UL LOGO ON SECONDARY SIDE IN SILKSCREEN
 6. FINAL FABRICATION:
 - A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER..PER IPC-5M-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
 - B. ALL VIAS THAT ARE PLACED ON EXPOSED PADS MUST BE PLUGGED WITH SOLDERMASK INK ON THE SIDE WHERE IT IS MASKED IN THE SOLDER MASK FILM.THIS IS TO AVOID SOLDER FLOW THROUGH VIA HOLE.
 7. FINISH:
 - A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
 - B. NICKEL THICKNESS. 100-200 MICROINCHES.
 - C. GOLD THICKNESS: 3-10 MICROINCHES.
 8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN SILKSCREEN ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V), DATE CODE (WWYY), AND RoHS COMPLIANT SYMBOL.
 9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
 - 10.MAXIMUM WARP OR TWIST SHALL NOT EXCEED 0.005" PER INCH


- 11.TESTING:
 - A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED
 - B. T-LINE IMPEDANCE TO BE TESTED OR GURANTEED WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED
- 12.MINIMUM TRACE WIDTH : 5 MILS
MINIMUM SPACING : 4.1 MILS
- 13.LAYER LADDER PROVIDED IN THE PCB SHOULD NOT BE MASKED
- 14.DESIGN TEAM:

IN SOLDER MASK LAYER, COPPER PAD HAS BEEN ENABLED INSTEAD OF MASK PAD FOR PROVIDING 1:1 SOLDER MASK OPENING FOR PADS ALL OVER THE BOARD.
CAM TEAM:
PLS DELETE NOTE 14 DURING GERBER GENERATION

STACK INFORMATION			IMPEDANCE			
LAYERS	TYPE	THICKNESS(MILS)				
TOP SIDE SOLDER MASK			SINGLE ENDED	OHM	DIFFERENTIAL	OHM
L1	TOP	COPPER-PLATING	1.30MILS	7.2MILS,50 OHM+/-10%	49.91 OHM	6.5/13/6.5 MILS, 95-99
L2	GND1	PREPREG	4.30 MILS			
		COPPER	0.65MILS			
		CORE	4.00MILS			
L3	SIG1	COPPER	0.65MILS	5MILS,50 OHM +/-10%	47.76 OHM	
		PREPREG	9.50MILS			
L4	PWR1	COPPER	0.65MILS			
		CORE	18.0MILS			
L5	PWR2	COPPER	0.65MILS			
		PREPREG	9.50MILS			
L6	SIG2	COPPER	0.65MILS	5MILS,50 OHM +/-10%	47.76 OHM	
		CORE	4.00MILS			
L7	GND2	COPPER	0.65MILS			
		PREPREG	4.30MILS			
L8	BOTTOM	COPPER-PLATING	1.30MILS	7.2MILS,50 OHM+/-10%	49.91 OHM	6.5/13/6.5 MILS, 95-99
BOTTOM SIDE SOLDER MASK			0.50 MILS			
TOTAL			61.10 MILS	BOARD THICKNESS : 0.062" +/-0.006",MATERIAL 370HR		
			1.55MM			



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+3.0/-3.0	PLATED	224
•	10.0	+3.0/-3.0	PLATED	310
•	12.0	+3.0/-3.0	PLATED	151
•	30.0	+3.0/-3.0	PLATED	5
•	39.0	+3.0/-3.0	PLATED	4
•	40.0	+3.0/-3.0	PLATED	80
•	40.16	+3.0/-3.0	PLATED	2
•	43.0	+3.0/-3.0	PLATED	8
■	95.0	+3.0/-3.0	PLATED	2
■	118.0	+2.0/-2.0	NON-PLATED	4
■	50.24x26.62	+3.0/-3.0	PLATED	2

UNLESS OTHERWISE SPECIFIED		SIGNATURES	DATE	COMPANY:  CYPRESS PERFORM		198 CHAMPION COURT SAN JOSE, CA 95134 (408) 943-2600	
DIMENSIONS ARE IN INCHES		DRAWN : VANAJA	12/06/14	CHECKED : PRAJITH		12/06/14	
TOLERANCES ON ANGLES +/- 2		ENGRG : SHREESHA		12/06/14			
2 PL DECIMALS +/- .010		ISSUED					
3 PL DECIMALS +/- .005							
THIRD ANGLE PROJECTIONS							
CYPRESS PROPRIETARY							
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DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY CYPRESS							
				FABRICATION DRAWING		SUPERSPEED EXPLORER KIT	
				SIZE C		FSQM NO	
				DWG NO		610-60190-01	
				REV		04	
				SCALE : 1/1		SHEET 1 OF 1	